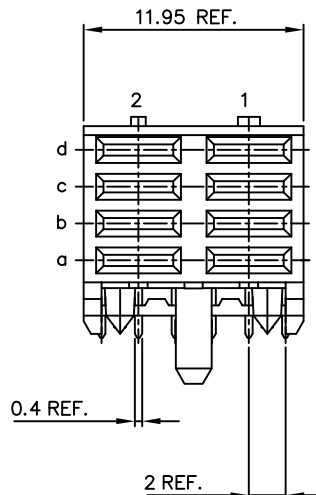
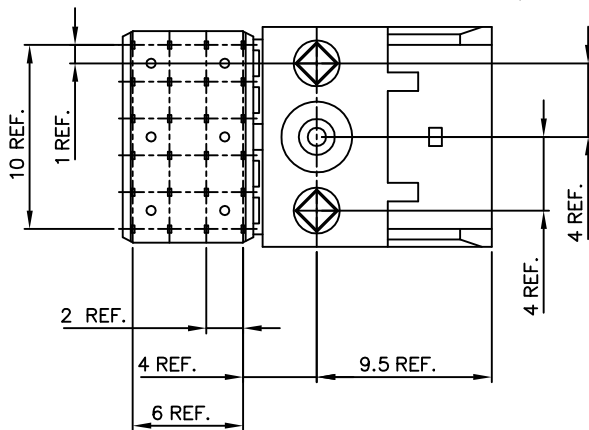
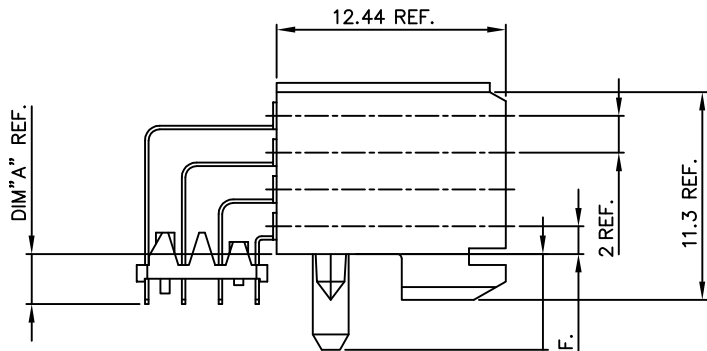
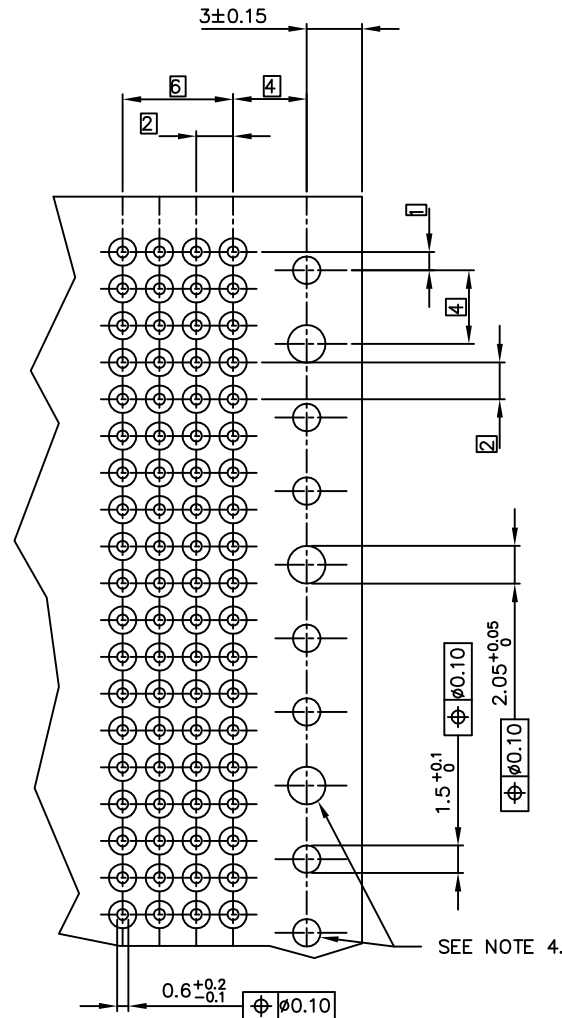
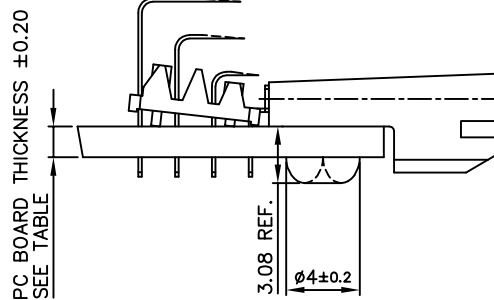


PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM "A"
70231-X01/X01LF	1.6	2.73
70231-X11/X11LF	2.4	3.53



PRODUCT AFTER HOT RIVETTING.



RECOMMENDED HOLE PATTERN,
COMPONENT SIDE.

NOTES:

- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- TERMINAL MATERIAL: PHOSPHOR BRONZE.
- PLATING SOLDER TAILS 2-8 μ m SnPb 90-97 OR 2-8 μ m
PURE Sn FOR LEAD FREE.
- INDICATED HOLES ARE UNPLATED.
- PRODUCT MARKING: PARTNUMBER & BATCH ID.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER
COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK
TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
70231-1YZ/1YZLF	0.8 μ m GOLD	1.3 μ m Ni MIN.
70231-2YZ/2YZLF	2 μ m GOLD	1.3 μ m Ni MIN.
70231-3YZ/3YZLF	1.3 μ m GOLD	1.3 μ m Ni MIN.
70231-9YZ/9YZLF	0.8 μ m GXT	1.3 μ m Ni MIN.

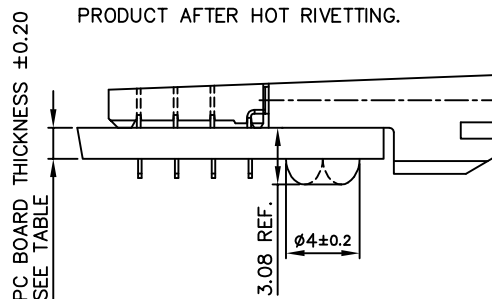
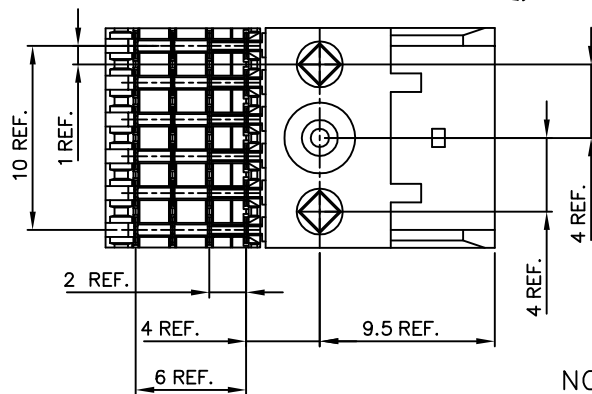
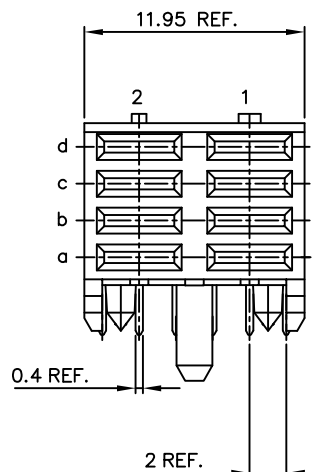
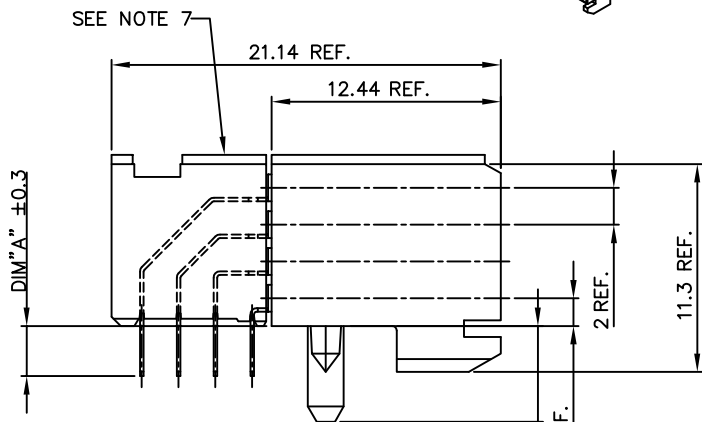
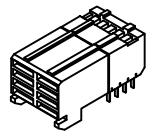
mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		ELECTRONICS	
ltr	ecn no	dr	date	linear		projection	title	product family	code
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E	H30759	EFE	940118	angles					
F	H40118	EFE	940211	dr	R.Trippe	900918			
G	V70769	DOB	970602	eng	H. Bouwknecht	940308			
H	V00578	LLA	000316	chr	A van Zanten	900918			
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sheet	revision	K	K						
index	sheet	1	2						

PDM: Rev.K

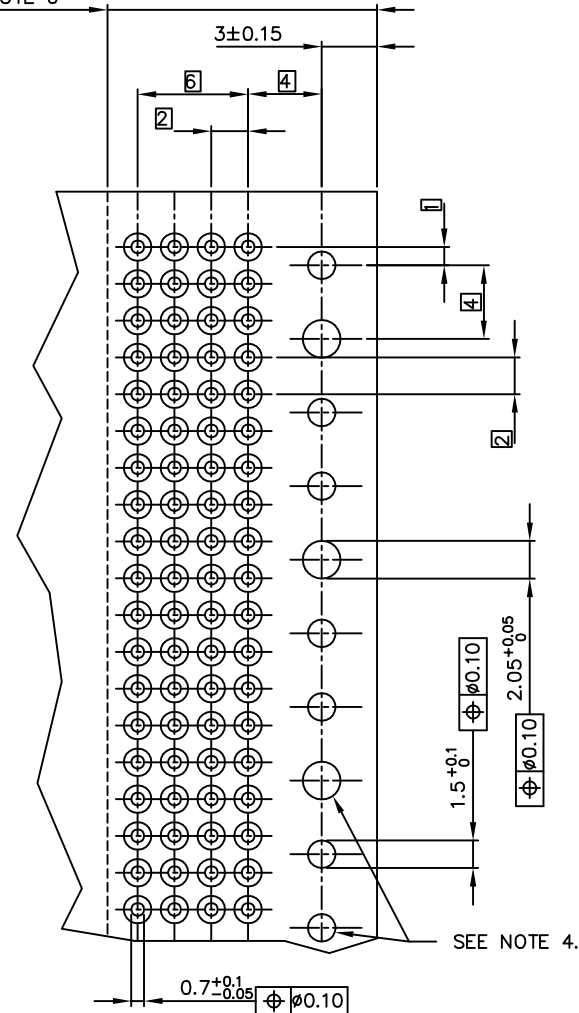
STATUS: Released

Printed: Feb 09, 2009

PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM "A"
70231-X02/X02LF	1.6	2.73
70231-X12/X12LF	2.4	3.53



14.64 REF. SEE NOTE 6





RECOMMENDED HOLE PATTERN,
COMPONENT SIDE.

NOTES:

- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm
PURE Sn FOR LEAD FREE.
- 4 INDICATED HOLES ARE UNPLATED.
- 5 PRODUCT MARKING: PARTNUMBER & BATCH ID.
- 6 SET BACK FOR PRESS BLOCK.
- 7 TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO
0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE
TAIL LENGTH BEFORE APPLICATION TO A BOARD
- 8 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER
COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 9 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK
TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
70231-1YZ/1YZLF	0.8 µm GOLD	1.3 µm Ni MIN.
70231-2YZ/2YZLF	2 µm GOLD	1.3 µm Ni MIN.
70231-3YZ/3YZLF	1.3 µm GOLD	1.3 µm Ni MIN.
70231-9YZ/9YZLF	0.8 µm GXT	1.3 µm Ni MIN.

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		 ELECTRONICS www.fciconnect.com	
ltr	ecr	no	dr	date	linear	projection	title	product family	code
K							RA FEMALE POWER STB 12 mm VERSION	NETRAL(tm)	213
					angles	mm	sizedwg no		sheet
					dr D. de Bil 970526	scale 5:1	A2	70231	2 of-
					engr P. Schalk 970526				
					chr P. Schalk 970526				
					app M. Coolmans 970526				
sheet	revision								
index	sheet								

PDM: Rev.K

STATUS: Released

Printed: Feb 09, 2006